

■ Absolute Maximum Rating

Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	I_F	20	mA
Peak Forward Current*	I_{FP}	160	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_D	85	mW
Electrostatic discharge	E_{SD}	400	V
Operation Temperature	T_{opr}	-25□+80	□
Storage Temperature	T_{stg}	-40□+80	□
Lead Soldering Temperature*	T_{sol}	Max. 230□ for 5sec Max.	

* I_{FP} Conditions □ Pulse Width ≤ 10msec duty ≤ 1/10

* T_{sol} Conditions □ 3mm from the base of the epoxy bulb

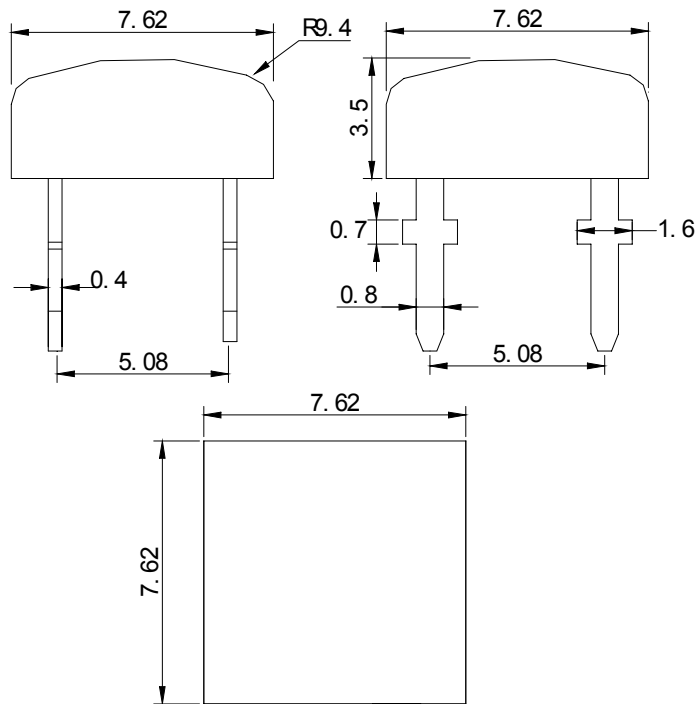
■ Typical Optical/ Electrical Characteristics

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20mA$	3.0	3.4	3.8	V
Reverse Current	I_R	$V_r=5V$	--	--	10	uA
50% Power Angle	$2\theta_{1/2}$	$I_F=20mA$	--	130	--	deg
Luminous Intensity	I_v	$I_F=20mA$	1000	1200	1500	mcd
Peak Wavelength	λ_P	$I_F=20mA$	--	--	--	nm
Recommend Forward Current	$I_F(\text{rec})$	--	--	10~20	--	mA

Notes:

1. Absolute maximum ratings $T_a=25□$.
2. Tolerance of measurement of forward voltage $\pm 0.1V$.
3. Tolerance of measurement of peak Wavelength $\pm 2.0nm$.
4. Tolerance of measurement of luminous intensity $\pm 15\%$.

■ Package Dimensions And Materials



Chip		Lens Color
Material	Emitting Color	
InGaN/SiC	White	Water clear

Notes:

1. All dimension units are millimeters.
2. All dimension tolerance is $\pm 0.2\text{mm}$ unless otherwise noted.
3. An epoxy meniscus may extend about 1.5mm down the leads.
4. Burr around bottom of epoxy may be 0.5mm max..

■ Reliability Performance

1. Test Items And Result

Test Classification	Test Item	Test Conditions	Test Duration	Sample Size	AC/RE
Life Test	Room Temperature DC Operating Life Test	Ta=25±5□□IF=20mA	1000 hrs	30pcs	0/1
Environment Test	Thermal Shock Test	-10±5□←→+100±5□ 5min. 10sec. 5min.	50 cycles	30 pcs	0/1
	Temperature Cycle Test	-40±5□←→+85±5□ 30min. 5min. 30min.	50 cycles	30 pcs	0/1
	High Temperature □ High Humidity Test	Ta=85±5□ RH =85%±0.5 %RH	1000 hrs	30 pcs	0/1
	High Temperature Storage	Ta=100±5□	1000 hrs	30 pcs	0/1
	Low Temperature Storage	Ta=-55±5□	1000 hrs	30 pcs	0/1
Mechanical Test	Resistance to Soldering Heat	Ta=230±5□	5sec.	30 pcs	0/1
	Lead Integrity	Load 2.5N(0.25kgf) 0° ~ 90° ~0°	3times	30 pcs	0/1

2. Criteria for Judging The Damage

Item	Symbol	Test Conditions	Criteria for Judgment	
			Min.	Max.
Forward Voltage	V _F	I _F =20mA		U.S.L.*1.2
Reverse Current	I _R	V _R =5V		U.S.L.*2.2
Luminous Intensity	I _V	I _F =20mA	L.S.L.**x0.7	

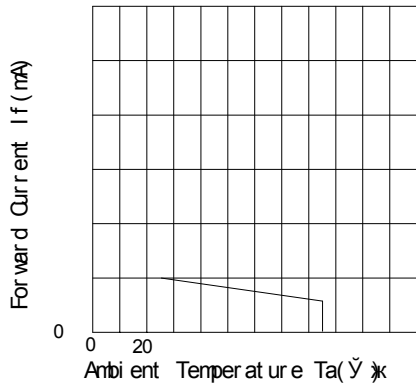
U.S.L.* : Upper Standard Level

L.S.L.** : Lower Standard Level

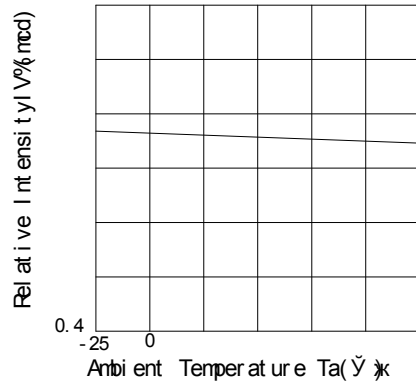
■ Typical Optical/Electrical Characteristics Curves

($T_a=25^\circ\text{C}$ Unless Otherwise Noted)

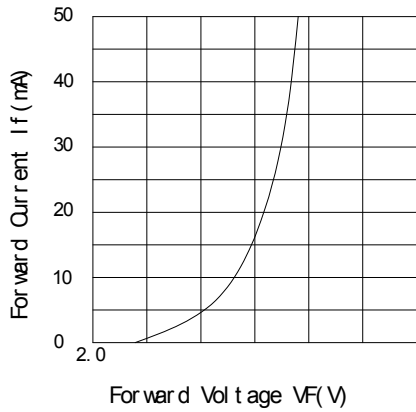
Forward Current vs. Ambient Temperature



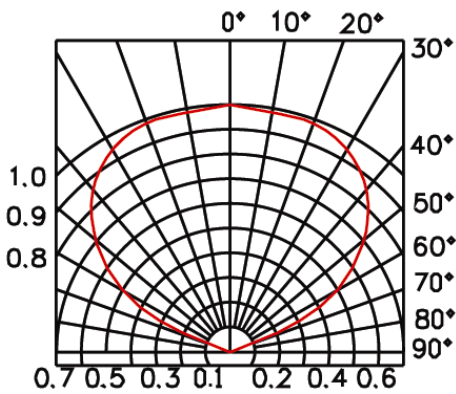
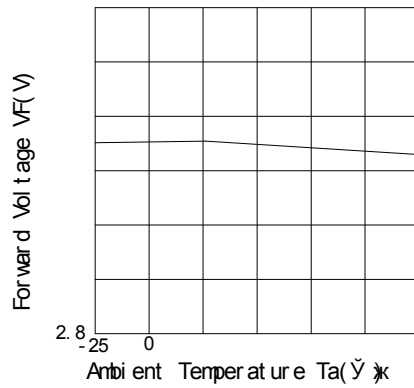
Relative Intensity vs. Ambient Temperature



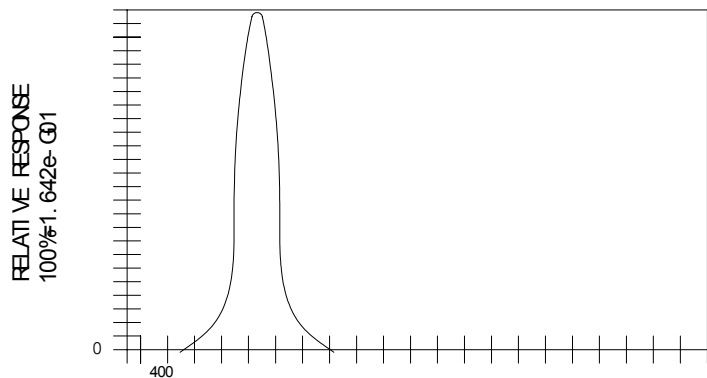
Forward Current vs. Forward Voltage



Forward Voltage vs. Ambient Temperature

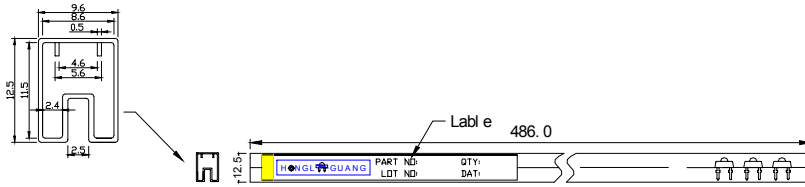


Luminous Spectrum ($T_a=25^\circ\text{C}$) SPECTRAL RADIANCE



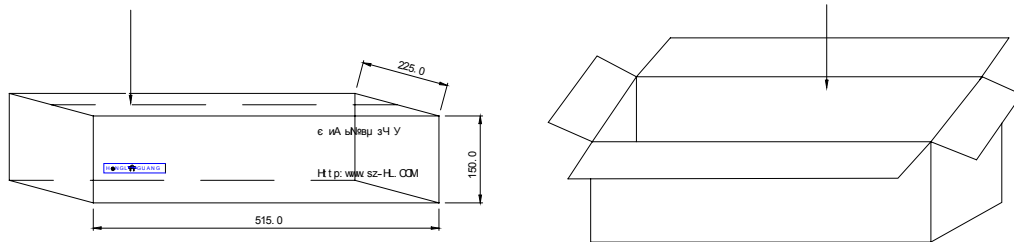
■ Package means

1.Package Adhesive Pipe.



Notes: Each Adhesive Pipe 60pcs.

2.Superficial Package paper boxes.



Notes: Each paper boxes 238 bar .